

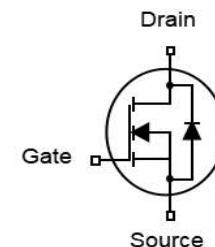


## Features

- N-Channel
- Low  $R_{DS(on)}$  & FOM
- Easy to use/drive
- 100% Avalanche Tested
- RoHS compliant
- 100% EAS Tested

$V_{DS}$	30	V
$R_{DS(on),TYP}@ V_{GS}=10\text{ V}$	4.7	$\text{m}\Omega$
$R_{DS(on),TYP}@ V_{GS}=4.5\text{ V}$	7.0	$\text{m}\Omega$
$I_D$	100	A

TO-252



Part ID	Package Type	Marking	Packing
ZT045N03D	TO-252	ZT045N03D	2500pcs/reel

## Absolute Maximum Ratings $T_A = 25^\circ\text{C}$ , unless otherwise specified

Symbol	Parameter	Rating	Unit
<b>Common Ratings (<math>T_c=25^\circ\text{C}</math> Unless Otherwise Noted)</b>			
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	30	V
$T_J$	Maximum Junction Temperature	150	$^\circ\text{C}$
$T_{STG}$	Storage Temperature Range	-55 to 150	$^\circ\text{C}$
$I_{DM}$	Drain Current-Continuous@ Current-Pulsed (Note 1)	$T_c = 25^\circ\text{C}$	A
<b>Mounted on Large Heat Sink</b>			
$I_D$	Drain Current-Continuous (Note 2)	$T_c = 25^\circ\text{C}$	A
		$T_c = 100^\circ\text{C}$	A
$P_D$	Maximum Power Dissipation	70	W
$R_{\theta JC}$	Thermal Resistance-Junction to Case	1.8	$^\circ\text{C}/\text{W}$
<b>Drain-Source Avalanche Ratings</b>			
EAS	Avalanche Energy, Single Pulsed	306	mJ



**Electrical Characteristics ( $T_J=25^\circ\text{C}$  unless otherwise noted)**

Symbol	Parameter	Condition	Min	Typ	Max	Unit
<b>Static Electrical Characteristics @ <math>T_J=25^\circ\text{C}</math> (unless otherwise stated)</b>						
V(BR)DSS	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}, I_D=250\mu\text{A}$	30	--	--	V
Idss	Zero Gate Voltage Drain Current	$V_{DS}=30\text{V}, V_{GS}=0\text{V}$	--	--	1	$\mu\text{A}$
IGSS	Gate-Body Leakage Current	$V_{GS}=\pm 20\text{V}, V_{DS}=0\text{V}$	--	--	$\pm 100$	nA
VGS(th)	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	1.0	1.7	2.2	V
RDS(on)	Drain-Source On-State Resistance	$V_{GS}=10\text{V}, I_D=20\text{A}$	--	4.7	5.5	$\text{m}\Omega$
RDS(on)	Drain-Source On-State Resistance	$V_{GS}=4.5\text{V}, I_D=20\text{A}$	--	7.0	8.9	$\text{m}\Omega$

**Dynamic Electrical Characteristics @  $T_J = 25^\circ\text{C}$  (unless otherwise stated)**

Ciss	Input Capacitance	$V_{DS}=15\text{V}, V_{GS}=0\text{V}, f=1\text{MHz}$	--	1970	--	pF
Coss	Output Capacitance		--	215	--	pF
Crss	Reverse Transfer Capacitance		--	178	--	pF
Rg	Gate Resistance	f=1MHz	--	1.0	--	$\Omega$
Qg	Total Gate Charge	$V_{DS}=15\text{V}, I_D=30\text{A}, V_{GS}=10\text{V}$	--	37.3	--	nC
Qgs	Gate-Source Charge		--	5.8	--	nC
Qgd	Gate-Drain Charge		--	7.7	--	nC

**Switching Characteristics**

Td(on)	Turn-on Delay Time	$V_{DS}=15\text{V}, I_D = 30\text{A}, R_G=2.7\Omega, V_{GS}=10\text{V}$	--	20	--	ns
Tr	Turn-on Rise Time		--	15	--	ns
Td(off)	Turn-Off Delay Time		--	60	--	ns
Tf	Turn-Off Fall Time		--	10	--	ns

**Source-Drain Diode Characteristics @  $T_J = 25^\circ\text{C}$  (unless otherwise stated)**

Is	Diode Forward Current		--	--	100	A
VSD	Forward on voltage	$I_S=30\text{A}, V_{GS}=0\text{V}$	--	--	1.2	V
Trr	Reverse Recovery Time	$T_J=25^\circ\text{C}, I_F=100\text{A}$ $di/dt=100\text{A}/\mu\text{s}$	--	32	--	ns
Qrr	Reverse Recovery Charge		--	12	--	nC

**Notes:**

1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature
2. EAS condition:  $T_J=25^\circ\text{C}$ ,  $V_{DD}=15\text{V}$ ,  $V_G=10\text{V}$ ,  $R_G=25\Omega$ ,  $L=0.5\text{mH}$ ,
3. Pulse Test: Pulse Width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 0.5\%$

### N- Channel Typical Characteristics

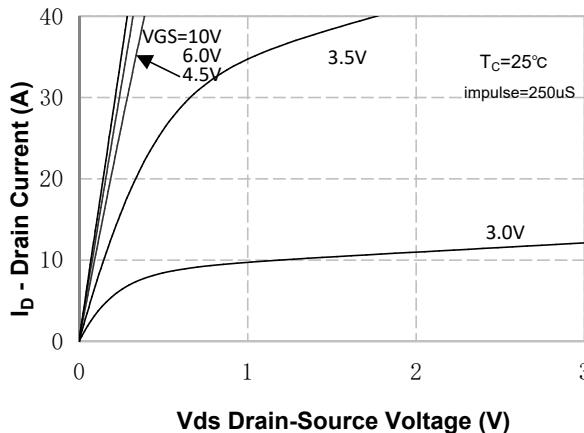


Figure 1. On-Region Characteristics

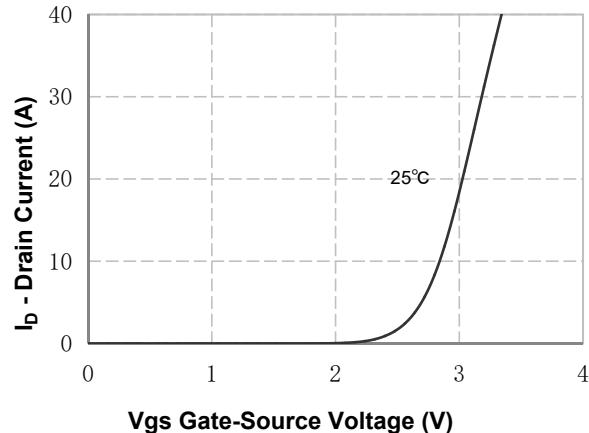


Figure 4. Transfer Characteristics

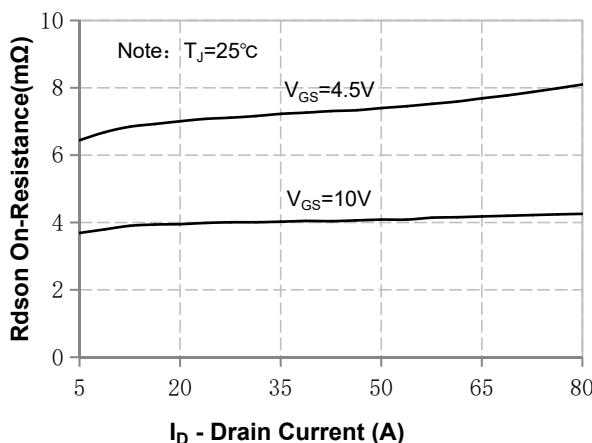


Figure 2. On-Resistance Variation vs Drain Current and Gate Voltage

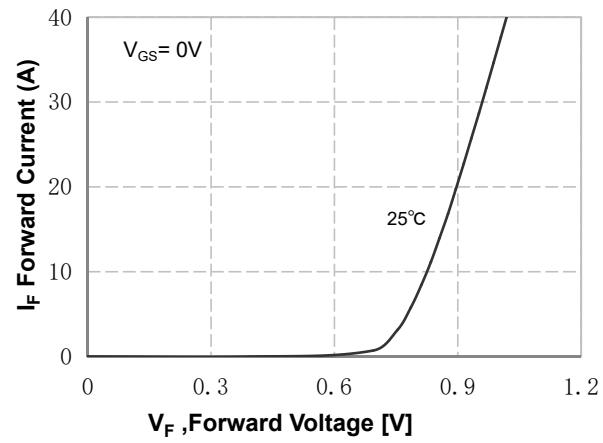


Figure 5. Body Diode Forward Voltage Variation vs Source Current

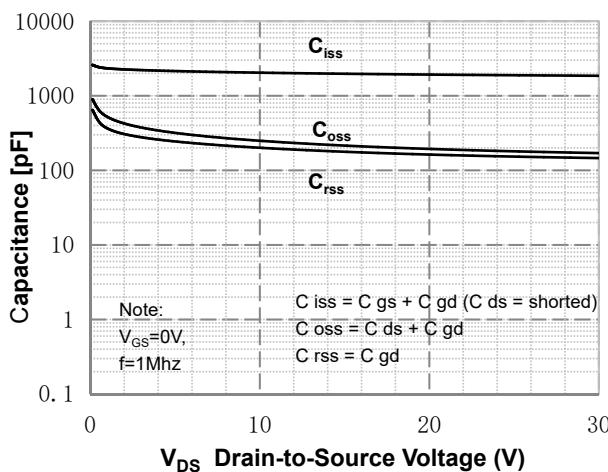


Figure 3. Capacitance Characteristics

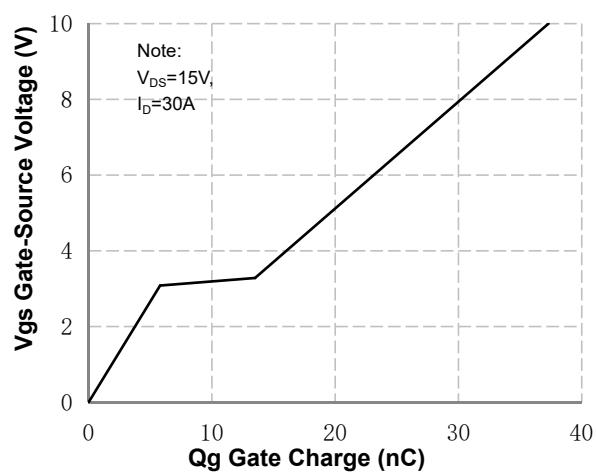
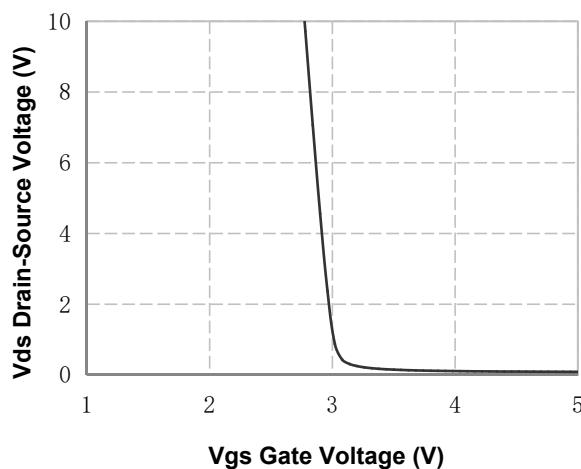
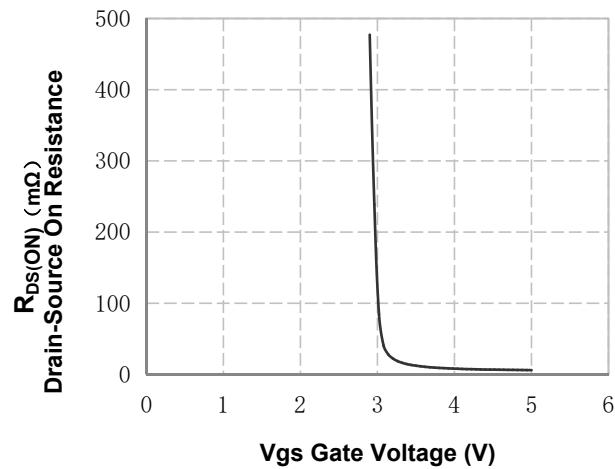


Figure 6. Gate Charge Characteristics

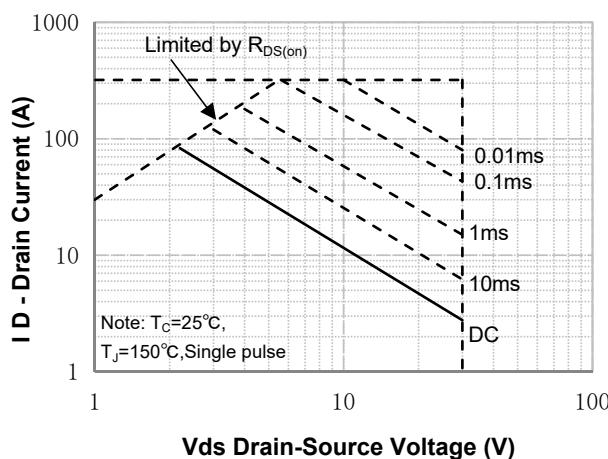
### N- Channel Typical Characteristics (Continued)



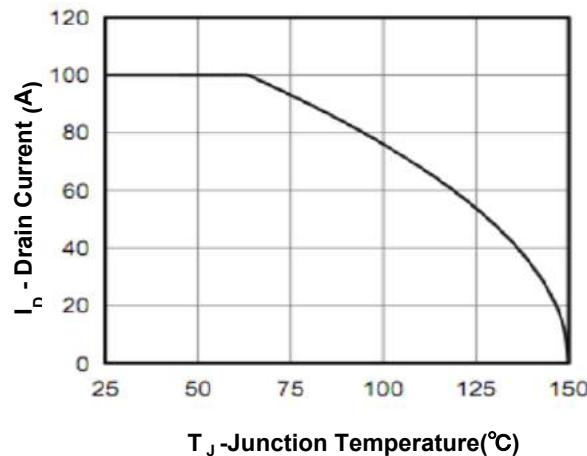
**Figure 7.** Vds Drain-Source Voltage vs Gate Voltage



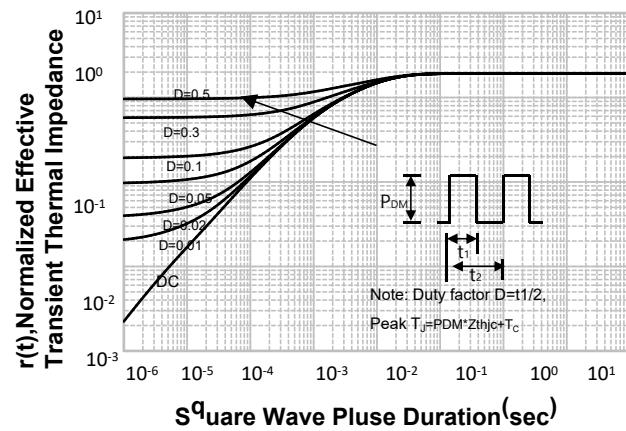
**Figure 9.** On-Resistance vs Gate Voltage



**Figure 8.** Maximum Safe Operating Area



**Figure 10.** Maximum Continuous Drain Current vs Temperature



**Figure 11.** Transient Thermal Response Curve

Figure A: Gate Charge Test Circuit and Waveform

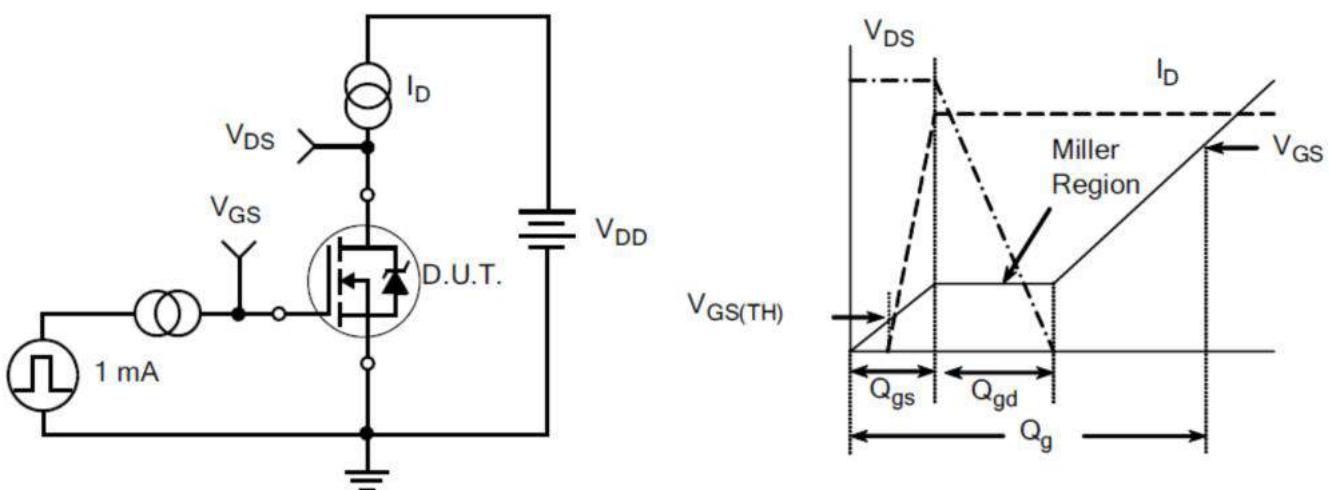


Figure B: Resistive Switching Test Circuit and Waveform

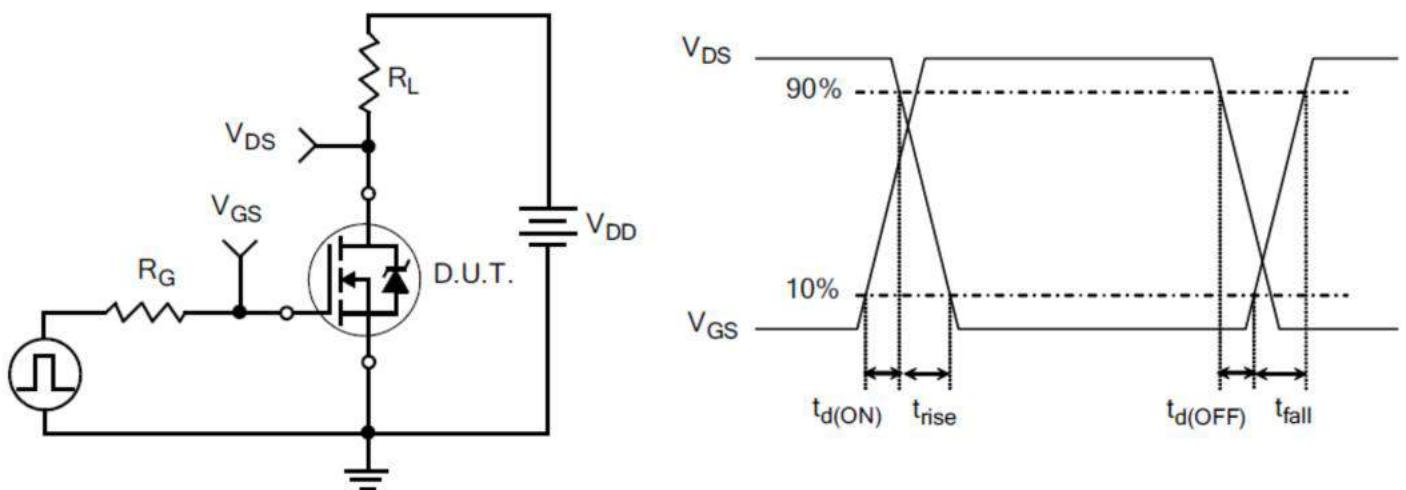
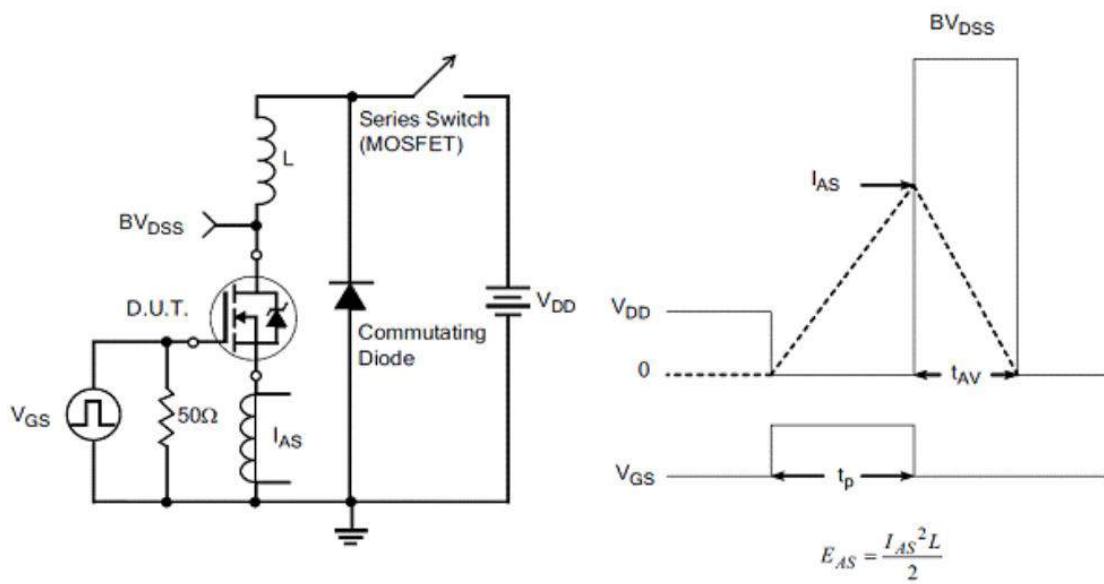
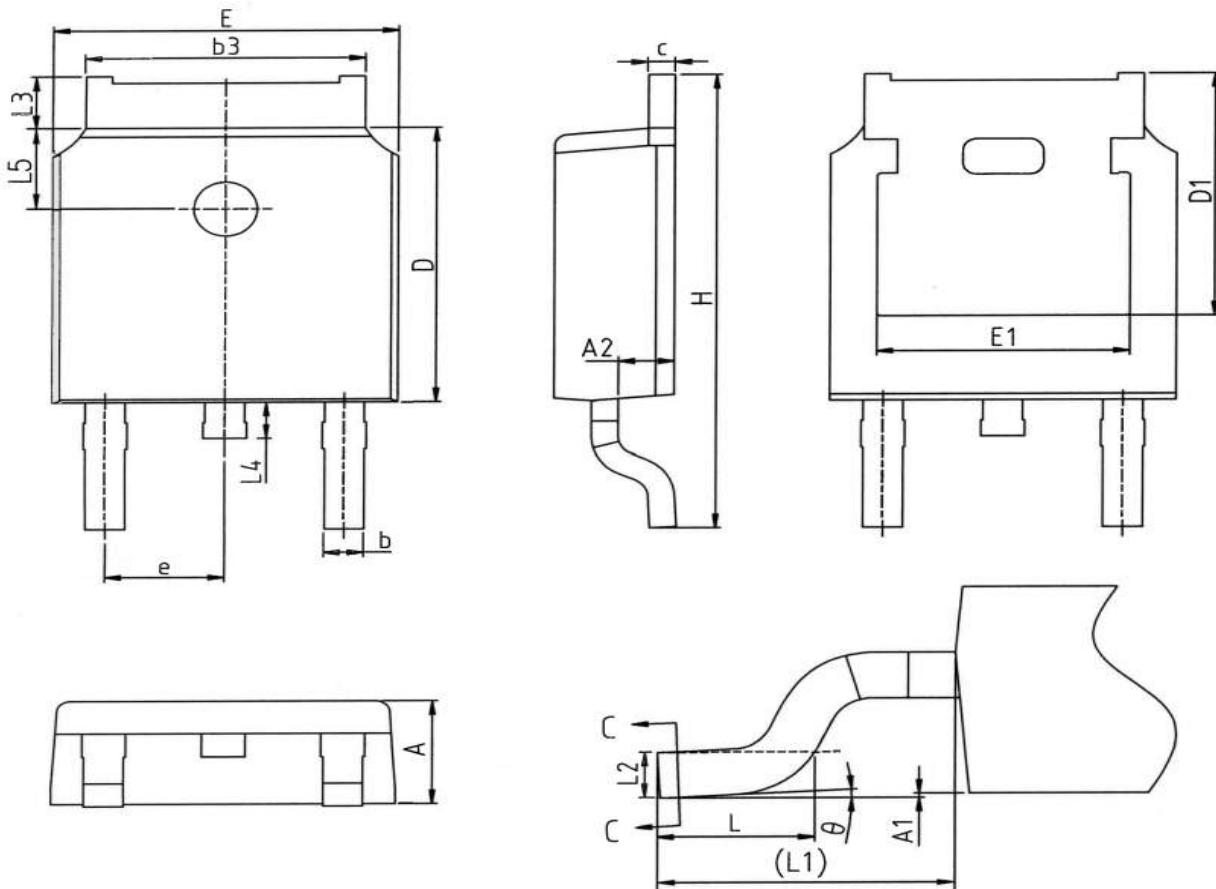


Figure C: Unclamped Inductive Switching Test Circuit and Waveform





## TO-252 Package Information



SYMBOL	mm		
	MIN	NOM	MAX
A	2.20	2.30	2.38
A1	0.00	-	0.12
A2	0.97	1.07	1.17
b	0.68	0.78	0.90
b3	5.20	5.33	5.46
c	0.43	0.53	0.61
D	5.98	6.10	6.22
D1	5.30REF		
E	6.40	6.60	6.73
E1	4.63	-	-
e	2.286BSC		
H	9.40	10.10	10.50
L	1.38	1.50	1.75
L1	2.90REF		
L2	0.51BSC		
L3	0.88	-	1.28
L4	0.50	-	1.00
L5	1.65	1.80	1.95
theta	0°	-	8°

## Customer Service

Sales and Service:

[zj@ztasemi.com](mailto:zj@ztasemi.com)